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US 20060134181 A1	US- PGPUB	20060622	11	Novel chocolate composition as delivery system for nutrients and medications	424/440	424/776; 426/660	Altaffer; Paul et al.
US 20060126623 A1	US- PGPUB	20060615	15	Methods and apparatus for implementing a protocol format capable of handling shared and dedicated radio resources	370/389		Huo; David Di
US 20060020419 A1	US- PGPUB	20060126		Iso-reflectance wavelengths	702/172		Benvegna; Dominic J.
US 20050266771 A1	US- PGPUB	20051201		Polishing pad with window	451/5		Wiswesser, Andreas Norbert
US 20050249177 A1	US- PGPUB	20051110		Hybrid wireless communications system	370/342	370/335	Huo, David D. et al.
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US 20050249110 A1	US- PGPUB	20051110		Peak-to-average power ratio control	370/208	370/318	Huo, David D. et al.
US 20050191947 A1	US- PGPUB	20050901		Retaining ring with shaped surface	451/41	451/285	Chen, Hung Chih et al.
US 20050173259 A1	US- PGPUB	20050811		Endpoint system for electro-chemical mechanical polishing	205/645	205/672; 451/5; 451/526	Mavliev, Rashid et al.
US 20050136800 A1	US- PGPUB	20050623		Polishing endpoint detection system and method using friction sensor	451/5	451/285; 451/41; 451/8	Miller, Gabriel Lorimer et al.
US 20050064802 A1	US- PGPUB	20050324		Polishing pad with window	451/285		Wiswesser, Andreas Norbert et al.
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US 20040242123 A1	US- PGPUB	20041202		Method for monitoring a substrate during chemical mechanical polishing	451/5	451/41; 451/8	Wiswesser, Andreas Norbert et al.
US 20040152396 A1	US- PGPUB	20040805		Substrate monitoring during chemical mechanical polishing	451/6		Wiswesser, Andreas Norbert et al.
US 20040116047 A1	US- PGPUB	20040617		Method and apparatus for detecting an end- point in chemical mechanical polishing of metal layers	451/6	257/E21.304	Wiswesser, Andreas Norbert et al.
US 20040082287 A1	US- PGPUB	20040429		Polishing pad with window	451/490		Wright, Jason R. et al.
US 20040082271 A1	US- PGPUB	20040429		Polishing pad with window	451/6		Wiswesser, Andreas Norbert et al.
US 20040058621 A1	US- PGPUB	20040325		Endpoint detection with multiple light beams	451/5	257/E21.23	Wiswesser, Andreas Norbert et al.
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US 20030104761 A1	US- PGPUB	20030605		Method and apparatus for measuring substrate layer thickness during chemical mechanical polishing	451/6		Wiswesser, Andreas Norbert et al.

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US 20030063598 A1	US- PGPUB	20030403		Methods and apparatus for implementing a protocol format capable of handling shared and dedicated radio resources	370/349	370/338	Huo, David Di
US 20030060127 A1	US- PGPUB	20030327		Sensor for in-situ pad wear during CMP	451/8		Kaushal, Tony S. et al.
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US 20030002532 A1	US- PGPUB	20030102		Telecommunications system having layered protocol with delimiter of payload	370/474	370/310	Huo, David
US 20020192316 A1	US- PGPUB	20021219		Novel chocolate composition as delivery system for nutrients and medications	424/776	514/263.31	Altaffer, Paulo et al.
US 20020013120 A1	US- PGPUB	20020131		Method and apparatus for optical monitoring in chemical mechanical polishing	451/6	257/E21.304; 451/10; 451/41; 451/8	Wiswesser, Andreas Norbert et al.
US 20010036793	US- PGPUB	20011101		Method and apparatus for	451/6	257/E21.304	Wiswesser, Andreas

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US 6607422 B1	USPAT	20030819		Endpoint detection with light beams of different wavelengths	451/6	257/E21.23; 451/41	Swedek; Boguslaw et al.
US 6524165 B1	USPAT	20030225		Method and apparatus for measuring substrate layer thickness during chemical mechanical polishing	451/6	451/288; 451/41; 451/8	Wiswesser; Andreas Norbert et al.
US 6506097 B1	USPAT	20030114		Optical monitoring in a two-step chemical mechanical polishing process	451/5	257/E21.23; 438/692; 451/36; 451/57; 451/6; 451/9	Adams; Bret W. et al.
US 6494766 B1	USPAT	20021217		Method and apparatus for measuring substrate layer thickness during chemical mechanical polishing	451/6	451/288; 451/41; 451/8	Wiswesser; Andreas Norbert et al.
US 6296548 B1	USPAT	20011002		Method and apparatus for optical monitoring in chemical mechanical polishing	451/8	257/E21.304; 451/288; 451/6	Wiswesser; Andreas Norbert et al.
US 6280289 B1	USPAT	20010828		Method and apparatus for detecting an end- point in chemical mechanical polishing of metal layers	451/6	257/E21.304; 451/287; 451/5	Wiswesser; Andreas Norbert et al.
US 6274854 B1	USPAT	20010814		Method and apparatus for baking out a gate valve in a semiconductor processing system	219/546	137/341; 219/201	Franklin; Timothy Joseph et al.
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US 6190234 B1	USPAT	20010220	Endpoint detection with light beams of different wavelengths	451/6	257/E21.23; 451/288; 451/41	Swedek; Boguslaw et al.
US 6162297 A	USPAT	20001219	Embossed semiconductor fabrication parts	118/715	204/298.11	Mintz; Donald M. et al.
US 6159073 A	USPAT	20001212	Method and apparatus for measuring substrate layer thickness during chemical mechanical polishing	451/6	451/288; 451/41; 451/8	Wiswesser; Andreas Norbert et al.
US 6000415 A	USPAT	19991214	Method and apparatus for positioning a restrictor shield of a pump in response to an electric signal	137/1	236/101R; 236/68R; 251/11	Huo; David Datong et al.
US 5965046 A	USPAT	19991012	Method and apparatus for baking out a gate valve in a semiconductor processing system	219/201	137/341; 219/444.1; 219/535; 219/540; 432/225	Franklin; Timothy Joseph et al.
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